



Material Content Data Sheet



Sales Product Name		TLE9202ED		Issued		20. July 2018		
MA#		MA001640472						
Package		PG-DSO-36-72		Weight*		538.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.798	1.63	1.63	16337	16337
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		448	
	non noble metal	copper	7440-50-8	240.973	44.75	44.80	447481	448063
	non noble metal	copper	7440-50-8	2.842	0.53	0.53	5277	5277
wire	non noble metal	copper	7440-50-8	2.842	0.53	0.53	5277	5277
encapsulation	organic material	carbon black	1333-86-4	0.823	0.15		1528	
	plastics	epoxy resin	-	32.083	5.96		59577	
	inorganic material	silicondioxide	60676-86-0	241.309	44.82	50.93	448106	509211
leadfinish	non noble metal	tin	7440-31-5	6.656	1.24	1.24	12360	12360
plating	noble metal	silver	7440-22-4	1.799	0.33	0.33	3341	3341
glue	plastics	epoxy resin	-	0.510	0.09		947	
	noble metal	silver	7440-22-4	2.404	0.45	0.54	4464	5411
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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